FUJIAN LANDI COMMERCIAL EQUIPMENT CO.,LTD

INFORMATION

Product No. : **X1G003851001500**

MODEL : **TG-5035CG-17N 26MHz**

INFO. No. : **A14-1279-0S**

DATE : **Jan. 7. 2015**

SEIKO EPSON CORPORATION

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INTRODUCTION

1. The contents is subject to change without notice.
   Please exchange the specification sheets regarding
   the product's warranty.

2. This sheet is not intended to guarantee or provide
   an approval of implementation of industrial patents.

3. We have prepared this sheet as carefully as possible.
   If you find it incomplete or unsatisfactory in any
   respect, We would welcome your comments.

This product is compliant with RoHS Directive.

This Product supplied (and any technical information furnished, if any) by SEIKO EPSON Corporation shall not be used for the development and manufacture of weapon of mass destruction or for other military purposes.
Making available such products and technology to any third party who may use such products or technologies for the said purposes are also prohibited.

This product listed here is designed as components or parts for electronics equipment in general consumer use.
We do not expect that any of these products would be incorporated or otherwise used as a component or part for the equipment, which requires an extra high reliability, such as satellite, rocket and other space systems, and medical equipment, the functional purpose of which is to keep life.

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[1] Characteristics

- Lead Free Reflowable and ultra small SMD(2.5 × 2.0 × 0.9 mm).
- Using the heat-resisting type AT cut quartz crystal allows almost the same temperature soldering as universal SMD IC.
- Operating supply voltage: 3.3V.

[2] Absolute maximum ratings

Parameter	Symbol	Value	Unit	Note
Supply voltage	V_{CC}-GND	-0.3 to 4.5	V	
Storage temperature range	T_stg	-40 to +90	°C	

[3] Operating range

Parameter		Symbol	Value			Unit	Note
			Min.	Typ.	Max.		
Power voltage		V_{CC}	3.0	3.3	3.6	V	V_{CC} = 3.3V ± 0.3V
		GND	0.0	0.0	0.0	V	
Operating temperature range		T_use	-30	+25	+85	°C	
Output load		Load_R	9	10	11	kΩ	
		Load_C	9	10	11	pF	
	DC-cut capacitor	C_C	0.01			μF	

DC-cut capacitor is not included in our TCXO. Please insert DC-cut capacitor (0.01uF Min.) in output line.

[4] Frequency characteristics

1) Output frequency 26.000000 MHz

2) Frequency characteristics

(Condition : V_{CC} = 3.3V, Load 10kΩ//10pF(DC cut), T_use =+25 °C)

Parameter	Symbol	Value			Unit	Note
		Min.		Max.		
Frequency tolerance	f_tol(osc)	-0.8	-	+0.8	$\times 10^{-6}$	T_use = +25°C ± 2°C Before Reflow
	f_tol *1	-2.0	-	+2.0	$\times 10^{-6}$	T_use = +25°C ± 2°C Reflow cycle : 2 times *2
Frequency / Temperature characteristics	fo-Tc	-0.5	-	+0.5	$\times 10^{-6}$	T_use = -30°C to +85°C (Based on frequency at +25°C)
Frequency / Load coefficient	fo-Load	-0.2	-	+0.2	$\times 10^{-6}$	Load :10kΩ // 10pF ± 10%each
Frequency / Voltage coefficient	fo-V_{CC}	-0.2	-	+0.2	$\times 10^{-6}$	V_{CC} = 3.3V ± 0.3V
Frequency aging	f_age	-1.0	-	+1.0	$\times 10^{-6}$	first year T_use =+25°C

*1 Include initial frequency tolerance and frequency deviation after reflow cycles.

*2 Measurement of frequency deviation is made 24h after reflow soldering.

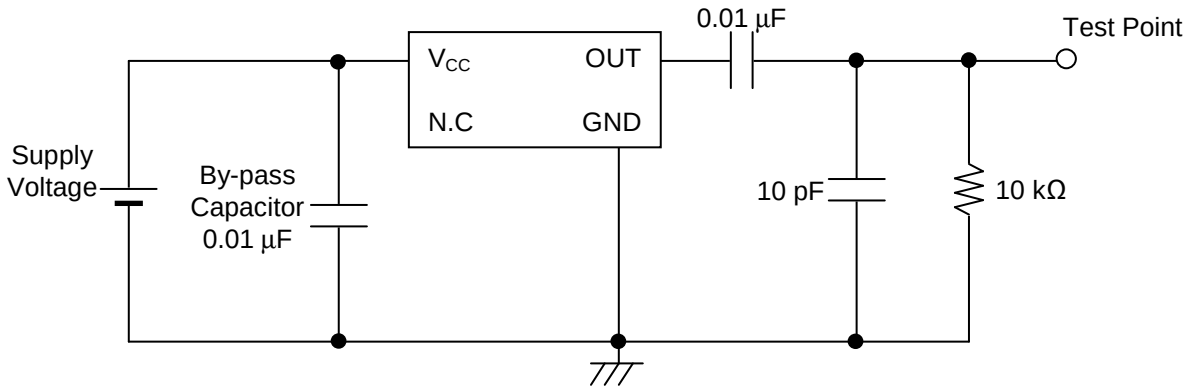
[5] Electrical characteristics

(Condition : V_{CC} = 3.3V, Load 10kΩ//10pF(DC cut), T_use =+25 °C)

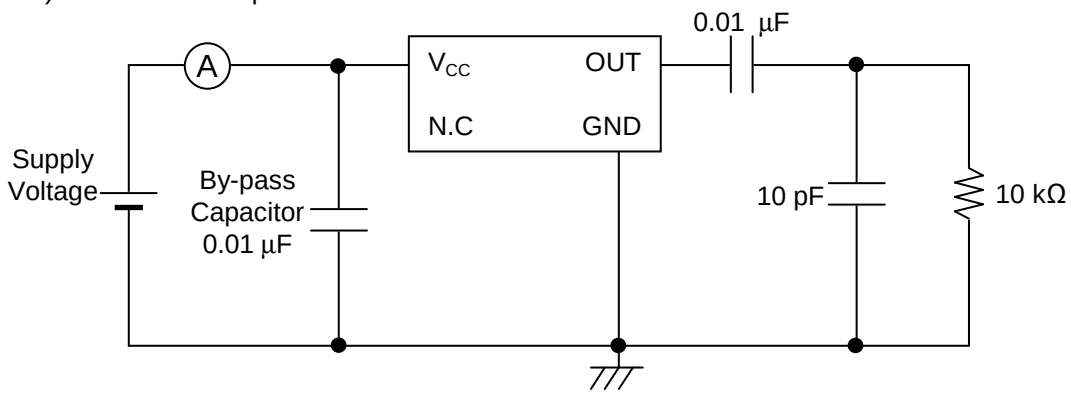
Parameter	Symbol	Value			Unit	Note
		Min.	Typ.	Max.		
Current consumption	I_{CC}	-	-	1.5	mA	
Output level	V_{PP}	0.8	-	1.5	V	Peak to peak voltage
Symmetry	SYM	40	-	60	%	GND Level
Harmonics	-	-	-	-8	dBc	
Startup time	t_str	-	-	2.0	msec	Until freqency has been reached within ±1 ppm of final freqency.
		-	-	2.0		Until output signal has been reached min90% of final amp.
SSB Phase noise	L(f)	-	-	-83	dBc /Hz	Offset:10 Hz
		-	-	-108		Offset:100 Hz
		-	-	-135		Offset:1 kHz
		-	-	-148		Offset:10 kHz
		-	-	-148		Offset:100 kHz
		-	-	-150		Offset:1 MHz

[6] Test circuit

1) Output Load : 10 kΩ//10 pF



2) Current consumption



3) Conditions

1. Oscilloscope: Impedance Min. 1 MΩ
   Input capacitance Max. 10 pF
   Band width Min. 300 MHz
   Impossible to measure both frequency and wave form at the same time.(In case of using oscilloscope's amplifier output, possible to measure both at the same time.)
2. CL includes probe capacitance.
3. A capacitor (By-pass:0.01 μF) is placed between V_{CC} and GND, and closely to TCXO.
4. Use the current meter whose internal impedance value is small.
5. Power Supply
   Impedance of power supply should be as lowest as possible.
6. GND should apply one point earth.

[7] Environmental and mechanical characteristics

(The company evaluation condition. we evaluate it by the following examination item and examination condition.)

No.	Item	Value *1 Freq. Tolerance [1×10^{-6}] *2 Electrical characteristics	Test method
1	High temp. storage *3	± 2.0	+85 °C × 1000 h
2	Low temp. storage *3	± 2.0	-40 ℃ × 1000 h
3	High temp. with humidity	± 2.0	+85 °C × 85%RH × 1000 h
4	Temp. cycle *3	± 2.0	-40 ℃ to +85 ℃ (30 min × 100 cycle/each)
5	Resistance to Soldering heat (Reflow characteristics)	± 1.0	Reflow furnace with the condition 3 times
6	Drop	± 2.0	150g dummy jig (SEIKO EPSON Standard) drop from 1500 mm height on the concrete 6 directions 3 times.
7	Vibration	± 2.0	10 Hz to 55 Hz amplitude 0.75 mm 55 Hz to 500 Hz acceleration 98 m/s^2 10 Hz → 500 Hz → 10 Hz 15 min / cycle 6 h (2 h × 3 directions)
8	ESD (MM)	± 1.0	200pF, 0Ω, 200V, Discharge 3 pulses
9	ESD (HBM)	± 1.0	100pF, 1.5kΩ, 2000V, Discharge 3 pulses
10	Solderability	Terminals must be 95 % covered with fresh solder	Dip termination into solder bath at +235 ℃ for 5 s (Using Rosin Flux)

Notes

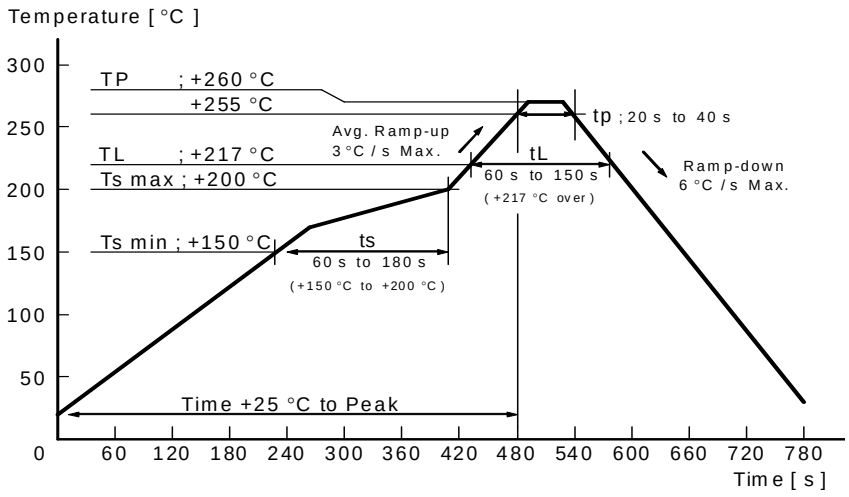
1.*1 each test is independent.

2.*2 measuring 2 h to 24 h later leaving in room temperature after each test.

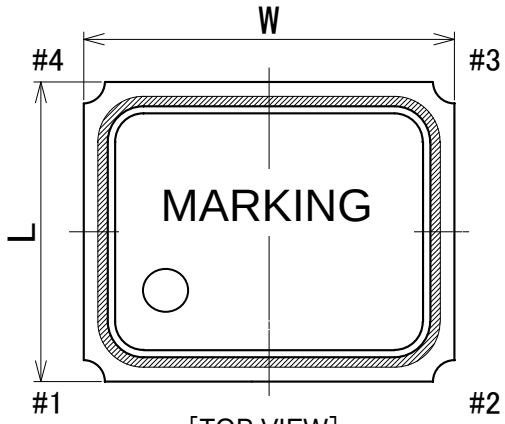
3.*3 Initial value shall be measured after 24 h storage at room temperature Pre-treatment

Pre-treatment : Bake (+125°C x 24 h) → Moisture soak (+85°C x 60 % x 168 h) → reflow (3 times)

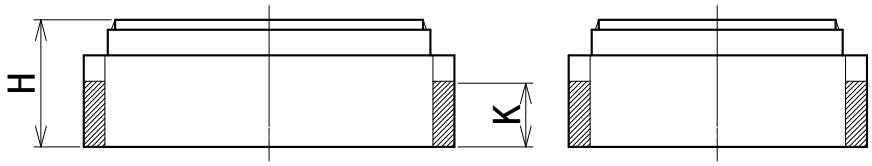
Reflow condition (follow to IPC / JEDEC J-STD-020C)



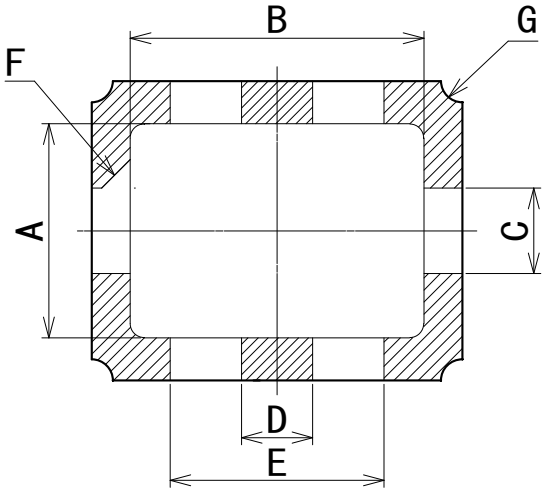
[8] Dimensions And Marking Layout



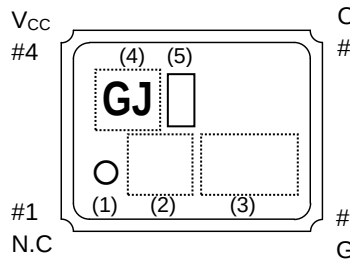
[TOP VIEW]



[SIDE VIEW]



[BOTTOM VIEW]



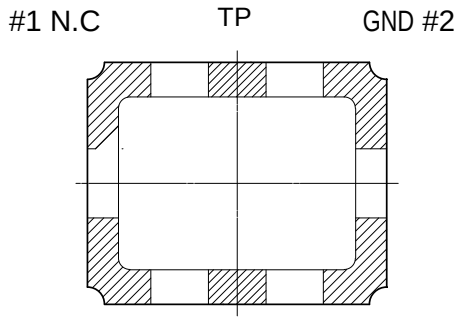
Marking

(1) 1Pin Mark
(2) Arbitrary marking area (2digits)
(3) TCXO LOT NO. (3digits)
(4) TCXO Model ID (GJ)
(5) Image recognition mark

Material

Ceramics(base)
Au coated nickel(terminal)
Fe-Ni-Co(lid)

CONNECTION



BOTTOM VIEW

(unit : mm)

Dim.	Min.	Typ.	Max.	Dim.	Min.	Typ.	Max.
W	2.35	2.50	2.65	D	0.40	0.50	0.60
L	1.85	2.00	2.15	E	1.35	1.50	1.65
H	0.70	0.80	0.90	F	---	C0.2	---
A	1.35	1.50	1.65	G	---	R0.15	---
B	1.95	2.10	2.25	K	---	0.45	---
C	0.50	0.60	0.70				

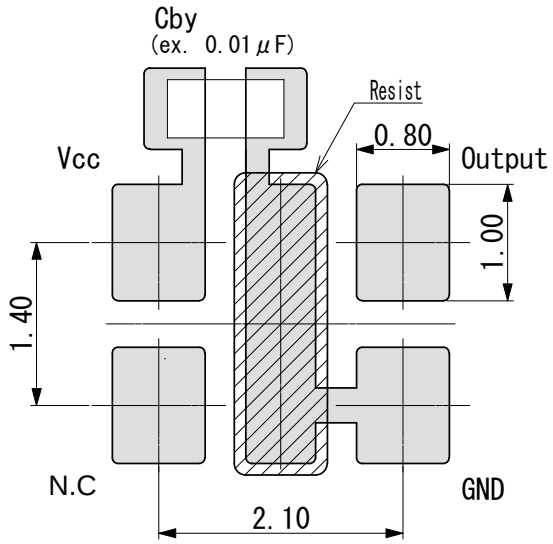
[9] Recommendable patterning

For actual design work, please consider optimum condition together with mounting density, reliability of soldering and mount ability etc.

Do not design any patterns except GND on the shaded area.

Soldering position

Unit: mm



[10] Handling precautions

Prior to using this product, please carefully read the section entitled “Precautions” on our Web site (http://www5.epsondevice.com/en/quartz/tech/precaution/) for instructions on how to handle and use the product properly to ensure optimal performance of the product in your equipment. Before using the product under any conditions other than those specified therein, please consult with us to verify and confirm that the performance of the product will not be negatively affected by use under such conditions.

In addition to the foregoing precautions, in order to avoid the deteriorating performance of the product, we strongly recommend that you DO NOT use the product under ANY of the following conditions:

(1) Mounting the product on a board using water-soluble solder flux and using the product without removing the residue of the flux completely from the board. The residue of such flux that is soluble in water or water-soluble cleaning agent, especially the residues which contains active halogens, will negatively affect the performance and reliability of the product.
(2) Using the product in any manner that will result in any shock or impact to the product.
(3) Using the product in places where the product is exposed to water, chemicals, organic solvent, sunlight, dust, corrosive gasses, or other materials.
(4) Using the product in places where the product is exposed to static electricity or electromagnetic waves.
(5) Applying ultrasonic cleaning without advance verification and confirmation that the product will not be affected by such a cleaning process, because it may damage the crystal, IC and/or metal line of the product.
(6) Touching the IC surface with tweezers or other hard materials directly.
(7) Using the product under any other conditions that may negatively affect the performance and/or reliability of the product.
(8) Using the product with power line ripple exceeding 200 mV(p-p) level.

Should any customer use the product in any manner contrary to the precautions and/or advice herein, such use shall be done at the customer’s own risk.

TAPING SPECIFICATION
テープ梱包基準書

1. APPLICATION 適用範囲

This document is applicable to 2.5 x 2.0 SMD package.

本基準書は、2.5 x 2.0 セラミックパッケージのテーピング梱包について規定する。

2. CONTENTS 目次

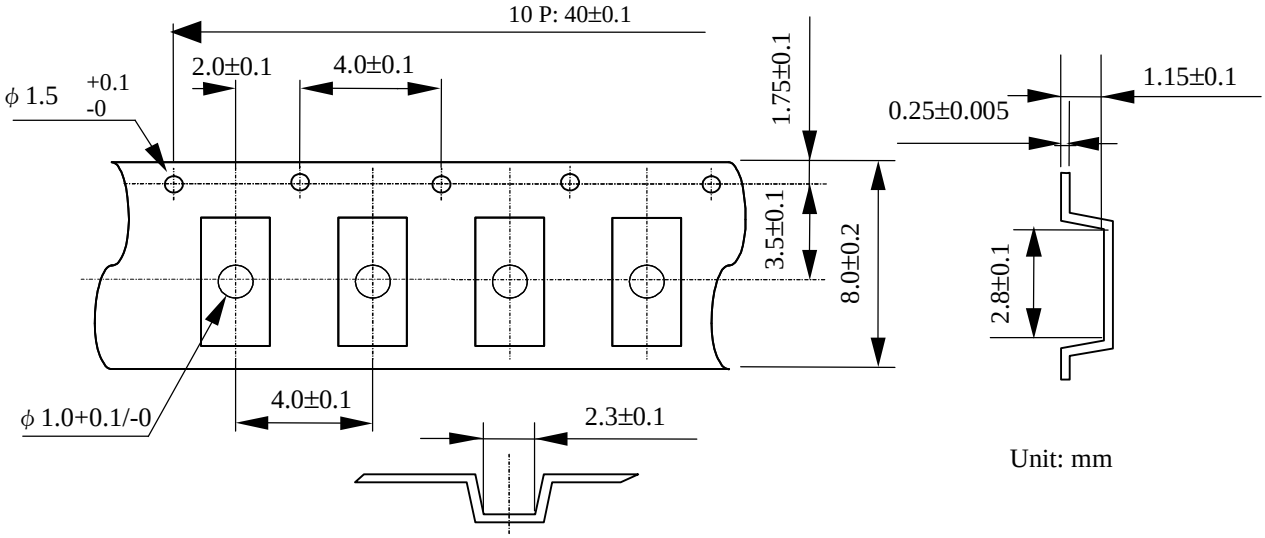
Item No.	Item	Page
[1]	**Taping specification** テーピング仕様	1 to 2
[2]	**Inner Sleeve** 袋への収納	3
[3]	**Shipping carton** 外装箱への収納	
[4]	**Marking** 表示	4
[5]	**Quantity** 収納数量	
[6]	**Storage environment** 保管環境	
[7]	**Handling** リール取扱い	

[1] Taping specification テーピング仕様

Subject to EIA-481 , IEC 60286.
「EIA-481」「IEC 60286」に準拠する。

(1) Tape dimensions TE0804L

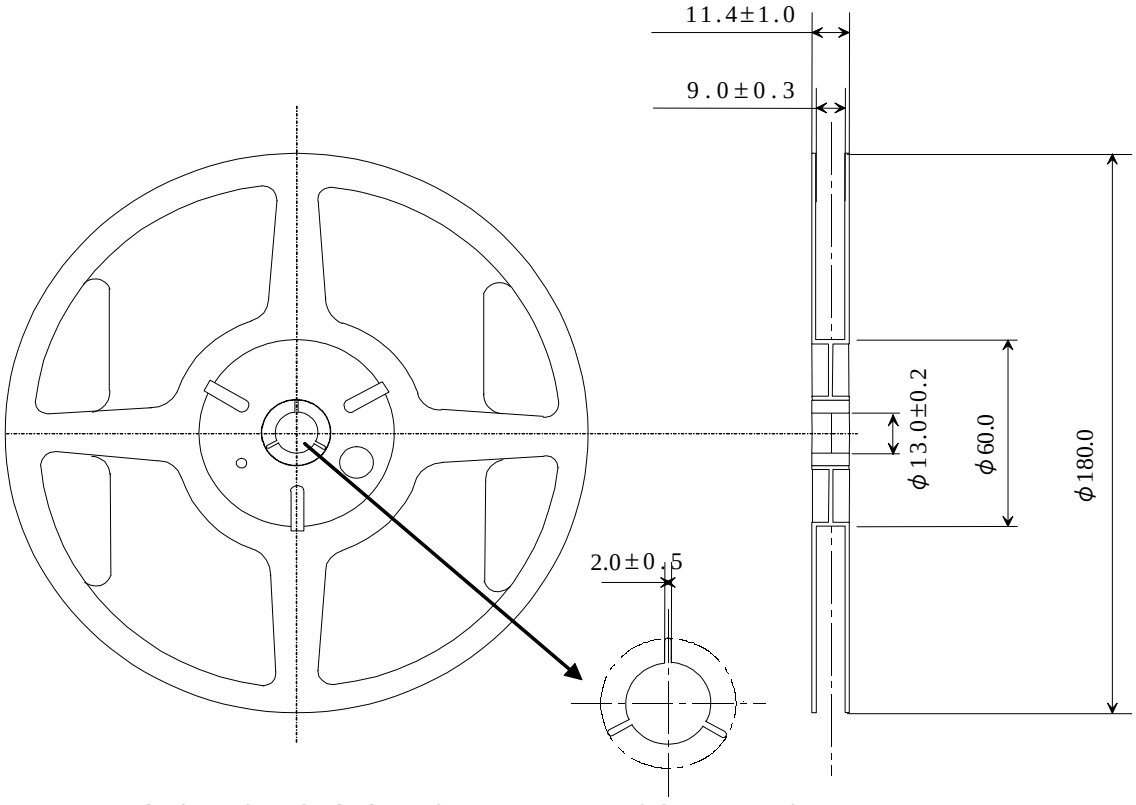
Material of the Carrier Tape キャリアテープ材質: PS (Black / Conductive 黒/導電性)
Material of the Top Tape トップテープ材質 : PET+PE



Unit: mm

(2) Reel dimensions

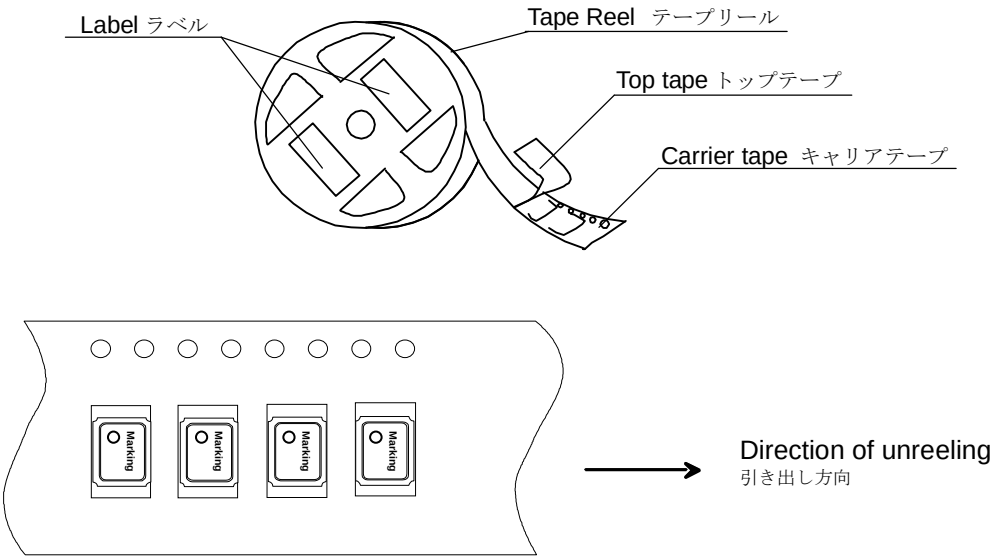
Material of the Reel リール材質: PS (Black / Conductive 黒/導電性)



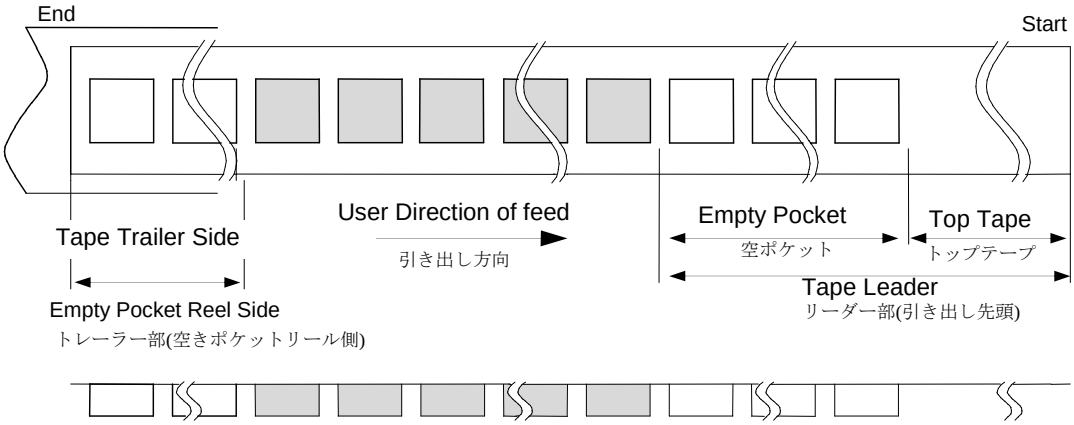
Form and Size of reel window shows are one of the example
リールの窓の形状は代表例を掲載。

(3) Packing 収納形態

(a) Tape & Reel デバイス収納方法



(b) Start & End Point 引き出し先頭側及びリール側の処理



Item 項目		Empty Space 空きスペース	Note 備考
Tape Leader (引き出し先頭側)	Top Tape	Min. 200 mm	Feeding in the Top tape, the tip is fixed with tape. トップテープ単独で繰り出し、先端はテープにより固定。
	Carrier Tape	Min. 150 mm	Winding method is a diagram of the above リールへの巻き取り方法は、上図の通り。
Tape Trailer (リール側)	Top Tape	Min. 0 mm	
	Carrier Tape	Min. 150 mm	Tip is fixed to the reel. 先端はリールに固定。

(4) Peel force of the cover tape トップテープの剥離強度

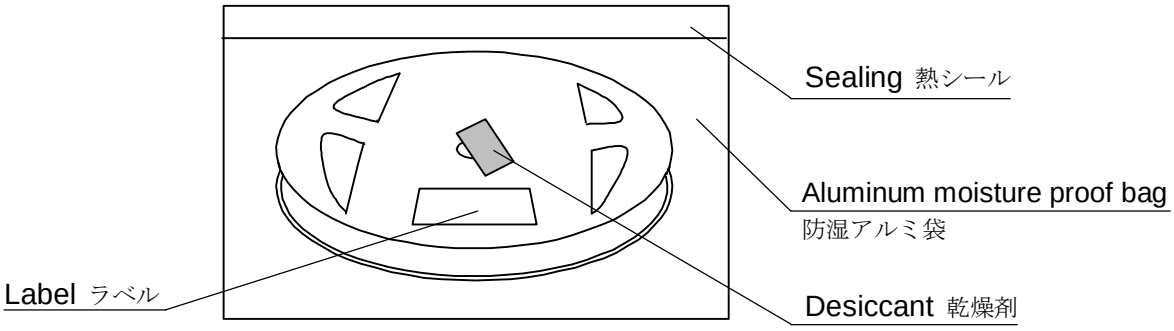
(a) Angle: cover tape during peel off and the direction of unreeling shall be 165° to 180°.
剥離角度:テープの接着面に対し 165～180 度とする。

(b) Peel speed: 300 mm/min.
剥離速度:300 mm/min とする。

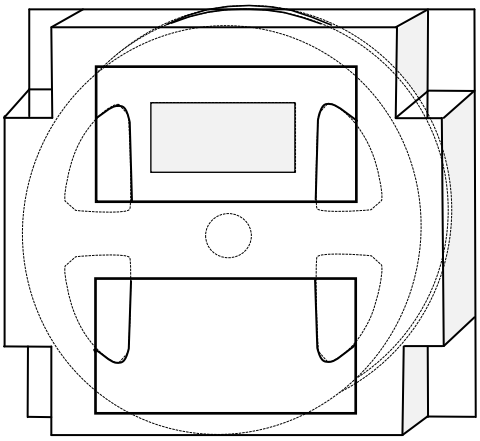
(c) Peel strength: 0.1 ~ 1.0 N.
剥離強度:0.1～1.0 N

[2] Inner sleeve

a) Packing to antistatic bag 袋への収納



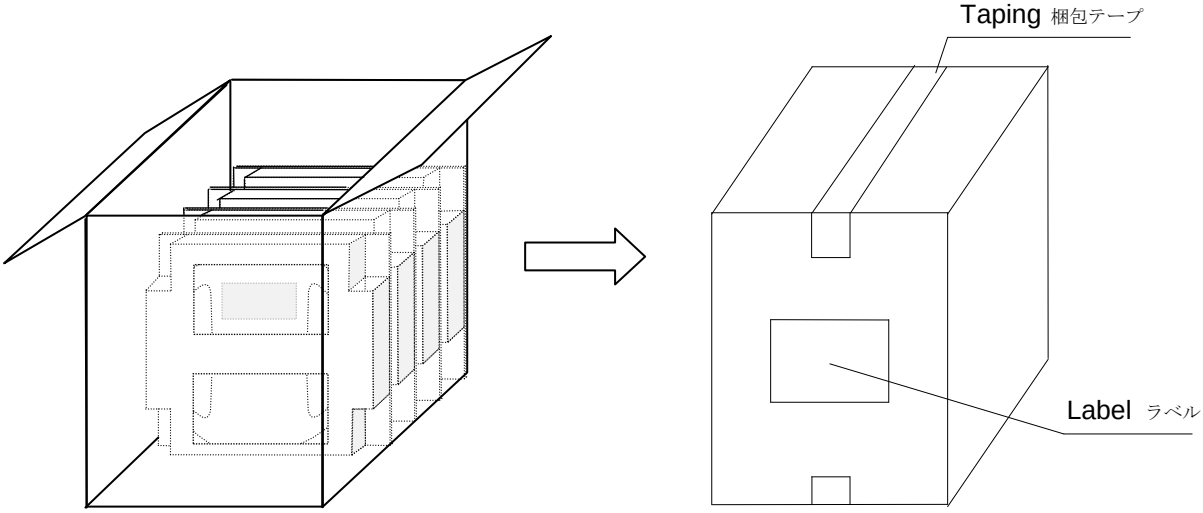
b) Packing to inner sleeve スリーブへの収納



*There is also a case to put the two reel.
* 2リール収納される場合もあります。

[3] Shipping Carton 外装箱への収納

- Put inner sleeve into an outer box.
  外装箱の中へ、スリーブを収納する。
- If there is space in the outer box, material is put in a shock absorbing together.
  空間ができた時は、クッション材を入れる。



[4] Marking 表示

(1) Reel marking リールへの表示

- Reel marking shall consist of

下記内容をリール表面に表示できるラベルを貼る。:

1) Parts name 製品名称
2) Quantity 製品数量
3) Manufacturing Date or symbol 製品の製造年月又はこれを示す記号
4) Manufacturer's Date or symbol 製品の製造業者又はその略号
5) Others (if necessary) その他必要事項

(2) Shipping carton marking 外装箱への表示

- Shipping carton marking shall consist of :

下記内容を外装箱表面に表示できるラベルを貼る。:

1) Parts name 製品名称
2) Quantity 製品数量

[5] Quantity 収納数量

- Maximum 2 000 pcs./reel 最大 2,000 個/リール
- Minimum 500 pcs./reel 最小 500 個/リール

[6] Storage environment 保管環境

(1) Before open the packing, we recommend to keep less than +30 °C and 85 %RH of Humidity, and to use it less than 6 months after delivery.

開梱前の製品は、温度 +30 °C、湿度 85 %RH 以下での保管をして下さい。
貴社納入後、袋未開封で 6 ヶ月以内の実装を推奨します。

(2) We recommend to open Package in immediately before use. After open Package, We recommend to keeps less than 6 month. No need dry air before soldering work if it is less than temperature +30 °C, 85 humidity %RH. When keeping six months are exceeded after the opening, it is recommended to be used after soldering is confirmed.

使用直前まで開梱せず、袋開封後は 6 ヶ月以内の実装を推奨します。
温度 +30 °C、湿度 85 %RH 以下では、はんだ付け作業前に乾燥不要です。
開封後保管 6 ヶ月を超えた場合は半田付け性を確認の上使用されることを推奨します。

(3) Not to storage with some erosive chemicals.

化学薬品類との同居を避ける。

(4) Nothing is allowed to put on the reel or carton to prevent mechanical damage.

内・外装箱がゆがまないようまた、外圧がかからないように保管して下さい。

[7] Handling リール取扱い

To handle with care to prevent the damage of tape, reel and products.

リールの取扱いについては、中のテープ・製品を変形させないようにして下さい。

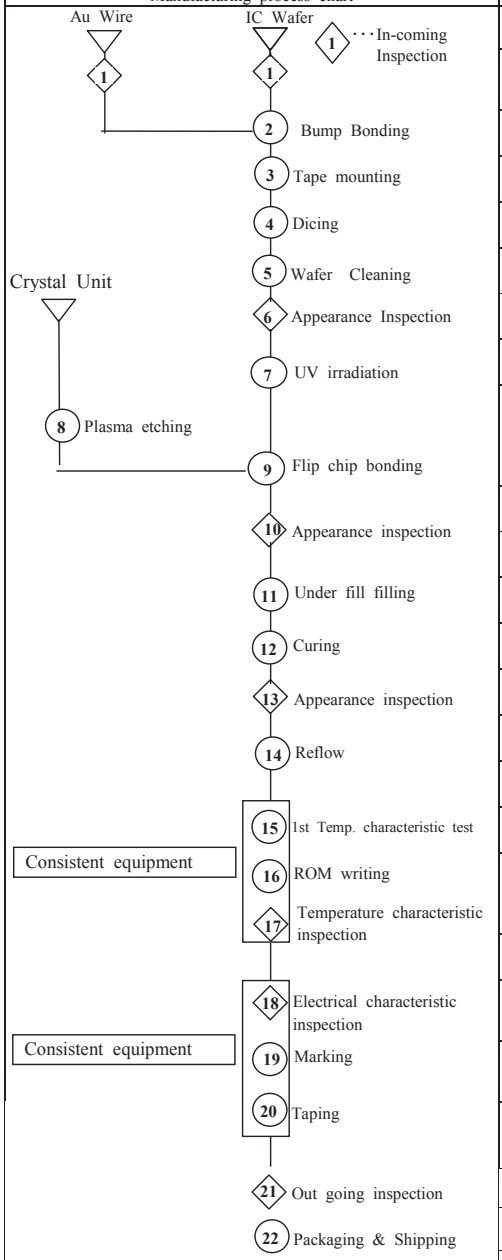
- PROCESS QUALITY CONTROL -

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SEIKO EPSON CORP.
Timing Device Business Unit

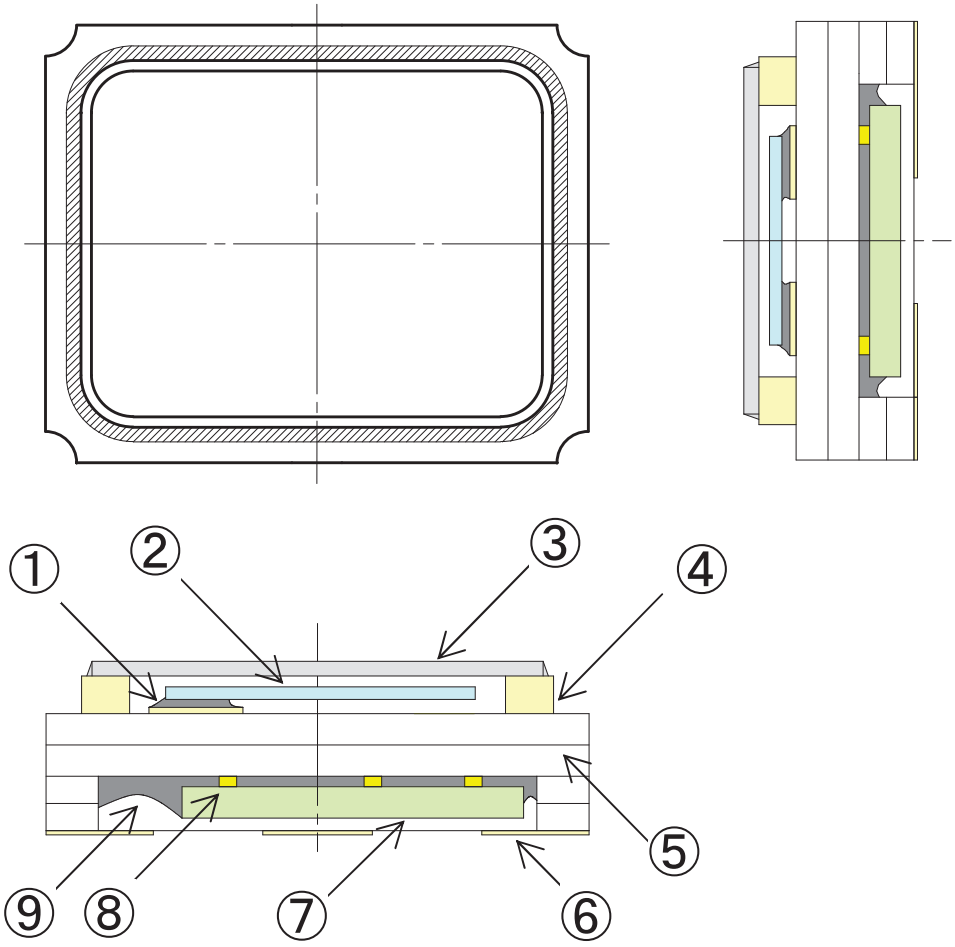
Approved	Checked	Prepared
H.koike		H.suzuki

No. TG5035CG - 00 – AVE - 2 CRYSTAL OSCILLATOR : TG-5035CG



No.	Section In Charge	Standards	Inspection, Control Item	Instruments	Inspection Methods	Record
1	EPSZ／ EPMY Sub contructor	Purchase specification Delivery card	Appearance	Visual inspection	Every lot	Data sheet
2	EPSZ／ EPMY Sub contructor	Specification (Work standard)	Heater temperature Bump dimension Shear strength	Thermometer Microscope Bond tester	Daily Sampling Sampling	Daily check sheet Data sheet Data sheet
3	EPSZ／ EPMY Sub contructor	Specification (Work standard)	Cutting condition Appearance	Visual inspection	Daily	Daily check sheet
4	EPSZ／ EPMY Sub contructor	Specification (Work standard)	Abrasion loss of Blade	Built-in gauge	Every batch	Tool change check sheet
5	EPSZ／ EPMY Sub contructor	Specification (Work standard)	Water resistance	Built-in meter	Daily	Daily check sheet
6	EPSZ／ EPMY Sub contructor	Specification (Work standard)	Dicing condition	Microscope	Sampling	Data sheet
7	EPSZ／ EPMY Sub contructor	Specification (Work standard)	UV condition	UV intensity meter	Daily	Daily check sheet
8	EPSZ／ EPMY Sub contructor	Specification (Work standard)	Flow rate of O2 and Ar	Built-in meter	Daily	Daily check sheet
9	EPSZ／ EPMY Sub contructor	Specification (Work standard)	Number of US tool shots Number of ejector needle shot. Heater temperature Bump dimension Shear strength	Built-in counter Built-in counter Thermometer Microscope Bond tester	100% 100% Daily Sampling Sampling	Tool change check sheet Daily check sheet Data sheet Data sheet
10	EPSZ／ EPMY Sub contructor	Specification (Work standard)	Flipchip bonding Condition	Microscope	Sampling	Data sheet
11	EPSZ／ EPMY Sub contructor	Specification (Work standard)	Chip coat storage temp. Pot lifetime	Thermometer Built-in timer	Daily 100%	Daily check sheet Tool change check sheet
12	EPSZ／ EPMY Sub contructor	Specification (Work standard)	Curing time Oven temperature	Timer Thermometer	Every batch Daily	Data sheet Daily check sheet
13	EPSZ／ EPMY Sub contructor	Specification (Work standard)	Appearance (FC & Under fill condition)	Microscope	100% Inspection	Data sheet
14	EPSZ／ EPMY Sub contructor	Specification (Work standard)	Reflow profile	Thermometer	Daily	Daily check sheet
15	EPSZ／ EPMY Sub contructor	Specification (Work standard)	Stage temperature	Thermometer	Daily	Daily check sheet
16	EPSZ／ EPMY Sub contructor	Specification (Work standard)	Stage temperature	Thermometer	Daily	Daily check sheet
17	EPSZ／ EPMY Sub contructor	Specification (Work standard)	Stage temperature Temperature characteristic	Thermometer Frequency counter	Daily 100% Inspection	Daily check sheet Data sheet
18	EPSZ／ EPMY Sub contructor	Specification (Work standard)	Frequency, Output-level Current drain, Frequency control range Master confirmation	Multi-meter Freq. counter Oscilloscope	100% Inspection	Data sheet
19	EPSZ／ EPMY Sub contructor	Specification (Work standard)	Appearance Marking	CCD camera	100% Inspection	Data sheet
20	EPSZ／ EPMY Sub contructor	Specification (Work standard)	Peeling off strength Direction	Peel back tester Visual inspection	Daily Sampling Delivery lot	Daily check sheet Data sheet
21	EPSZ／ EPMY Sub contructor	Specification (Work standard)	Frequency, Current drain, Appearance, Dimension	Freq. counter,Multi-meter, Visual inspection Calipers	Sampling	Data sheet
22	Production Control Department (EPSZ/EPMY Sub contructor & EPMY & Ina Plant)	Specification (Work standard)	Quantity	Visual inspection	Sampling Delivery lot	Data sheet Delivery record

Structure diagram. TG-5035CG



LIST		
Name of part		Specification
1	XTAL adhesives	Ag paste
2	XTAL chip	AT cut
3	Lid	Fe – Ni – Co
4	Seam ring	Kovar ＋ Ni ,Au
5	Base	Ceramic PKG
6	Terminal	Au coated , Ni
7	IC	CMOS
8	FC bump	Au
9	UF	Potting resin
10		

TCE11-CO-074_02		
MGR.	CHK.	ENG.
Y.Shishido		A.Kakumae

RELIABILITY TEST DATA

Product Name : TG-50xxCG series

The Company evaluation condition

We evaluate environmental and mechanical characteristics by the following test condition . **OUT10-E31-40M**

No.	ITEM	TEST CONDITIONS	VALUE *1		TEST Qty [n]	FAIL Qty [n]
			Δ f / f *2 [1 × 10^{-6}]	Electrical characteristics		
1	High temperature storage	+85 °C × 1 000 h	*3 ± 2.0	Satisfy output level after test	22	0
2	Low temperature storage	-40 °C × 1 000 h	*3 ± 2.0		22	0
3	High Temperature with Humidity	+85 ± 2 °C × 85 ± 5 %RH × 1 000 h	*3 ± 2.0		22	0
4	Temperature cycle	-40 °C ⇔ +85 °C 30 min at each temp. 1000 cycles	*3 ± 2.0		22	0
5	Resistance to soldering heat	Convection reflow soldering furnace (3 times)	± 1.0		22	0
6	Drop	150g dummy jig (Epson Toyocom Standard) drop from 1500 mm height on the concrete 6 directions 3 times.	± 2.0		22	0
7	Vibration	10 Hz to 55 Hz amplitude 0.75 mm 55 Hz to 500 Hz acceleration 98 m/s^2 10 Hz → 500 Hz → 10 Hz 15 min / cycle 6 h (2 h × 3 directions)	± 2.0		22	0
8	ESD (MM)	200pF 0Ω 200V , Discharge 3 pulses	± 1.0		22	0
9	ESD (HBM)	100pF 1.5kΩ 2000V , Discharge 3 pulses	± 1.0		22	0
10	Solderability	Dip termination into solder bath at +235 °C ± 5 °C for 5 s (Using Rosin Flux)	Termination must be covered with fresh solder more than 95 % of dip area.		11	0

Notes

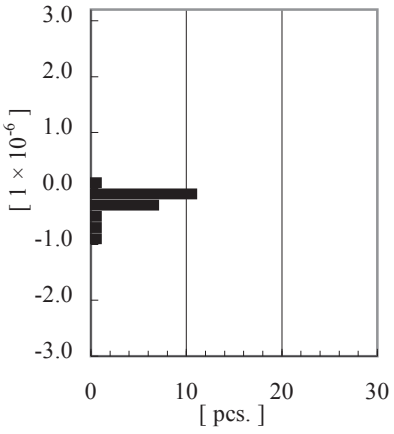
1. *1 Each test done independently.
2. *2 Measuring 2 h to 24 h later leaving in room temperature after each test.
3. *3 Initial value shall be measured after 24 h storage at room temperature Pre-treatment
   Pre-treatment : Bake (+125 ℃ × 24 h) →Moisture soak (+85 ℃ × 60 % × 168 h) →reflow (3 times)

Qualification Data

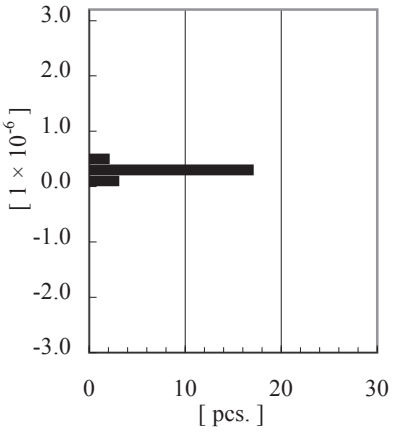
Product Name : TG-50xxCG series

df / f

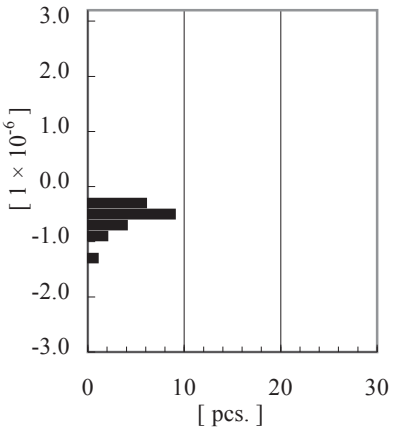
1. High temp. storage
+85 °C × 1 000 h



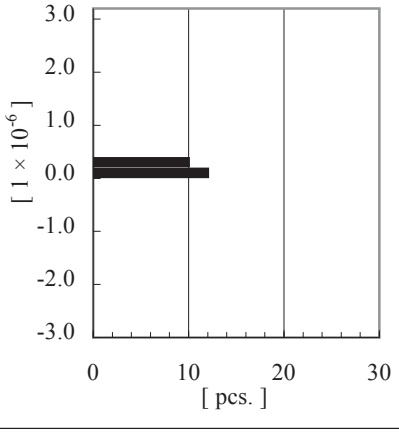
2. Low temp. storage
-40 °C × 1 000 h



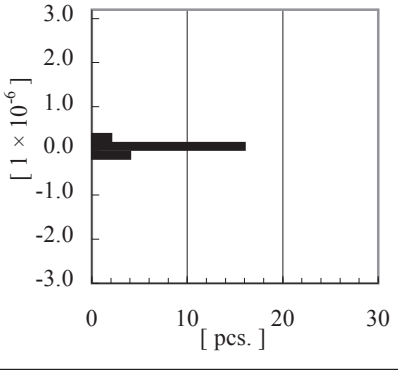
3. Temp. humidity storage
+85 °C × 85 %RH × 1 000 h



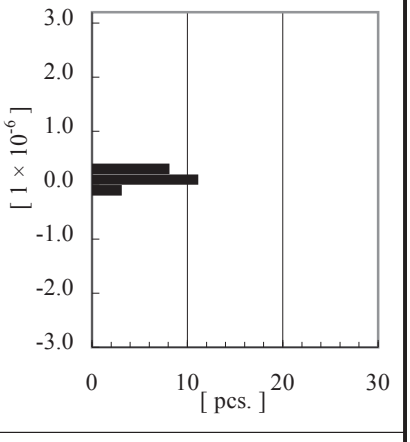
4. Temp. cycle
-40 °C ⇔ +85 °C
1000 cycles



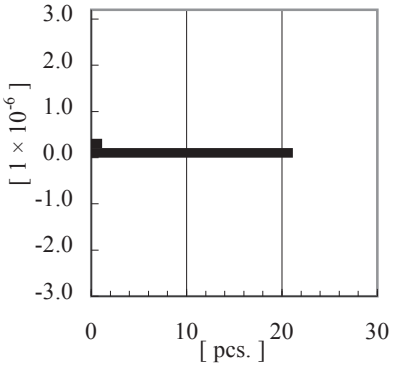
5. Resistance to soldering heat
For convention reflow soldering furnace (3 times)



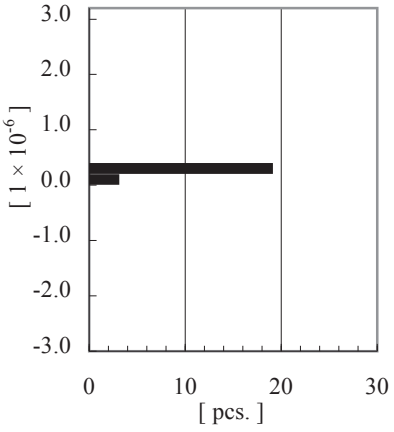
6. Drop
1500 mm × 6 times



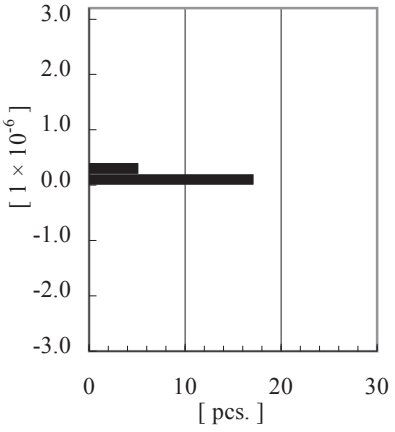
7. Vibration
10 Hz to 55 Hz amplitude 0.75 mm
55 Hz to 500 Hz acceleration 98 m/s^2
15 min / cycle
6 h (2 h × 3 directions)



8. ESD (MM)
200pF 0Ω 200V



9. ESD (HBM)
100pF 1.5kΩ 2000V



Qualification Data